

CKT	DIM A	DIM B	DIM C	DIM D	DIM E
005	8.84	3.20	6.34	6.14	7.44
010	12.84	7.20	10.34	10.14	11.44

NOTES:

1. MATERIAL:
  - 1.1 HOUSING: PA9T, HIGH TEMP.UL94V-0; COLOR:WHITE.
  - 1.2 CONTACT: COPPER ALLOY
  - 1.3 FITTING NAIL: STAINLESS
2. FINISH:
  - 2.1 CONTACT:
    - 50u" MIN NICKEL UNDERPLATING OVERALL.
    - 1: 1u" MIN. GOLD ON CONTACT AND GOLD FLASH ON SOLDER
  - 2.2 FITTING NAIL:
    - 50u" MIN. NICKEL UNDERPLATING OVERALL.
    - 80u" MIN. MATTE TIN(LEAD FREE) PLATING
3. SPEC. PLS. REFER TO PS-52200-XXXXX-XXX
4. PACKAGE PLS. REFER TO 52200-XXXXX-XX-TRP
5. PART NUMBER
 

52200-XXX X X -XXX

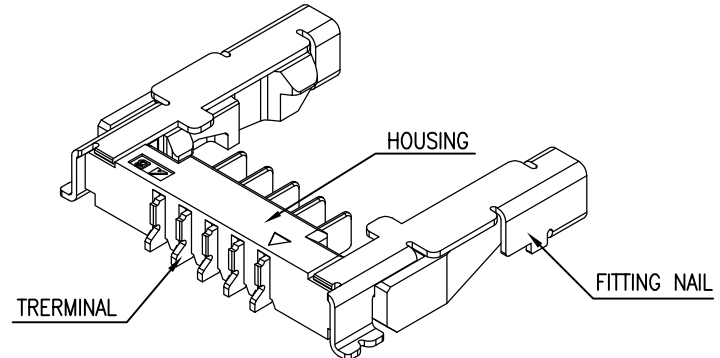
NO OF CKT	CODE	LOGO	PACKAGE
	001	ACES	52200-XXXXCR-00

PACKING

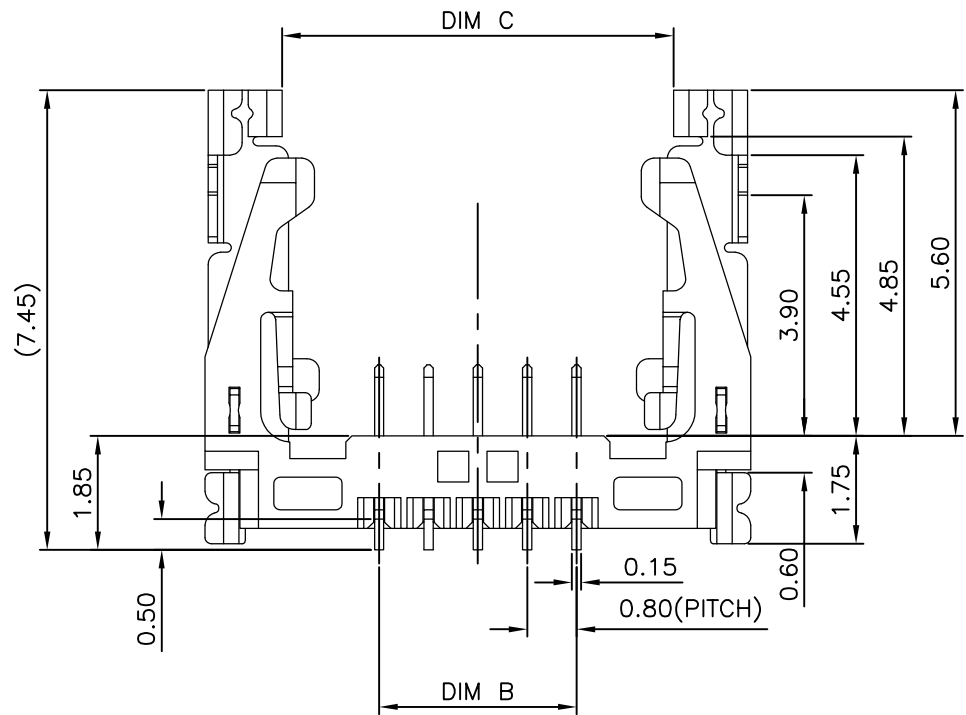
4:TAPE & REEL WITH MYLAR

PLATING

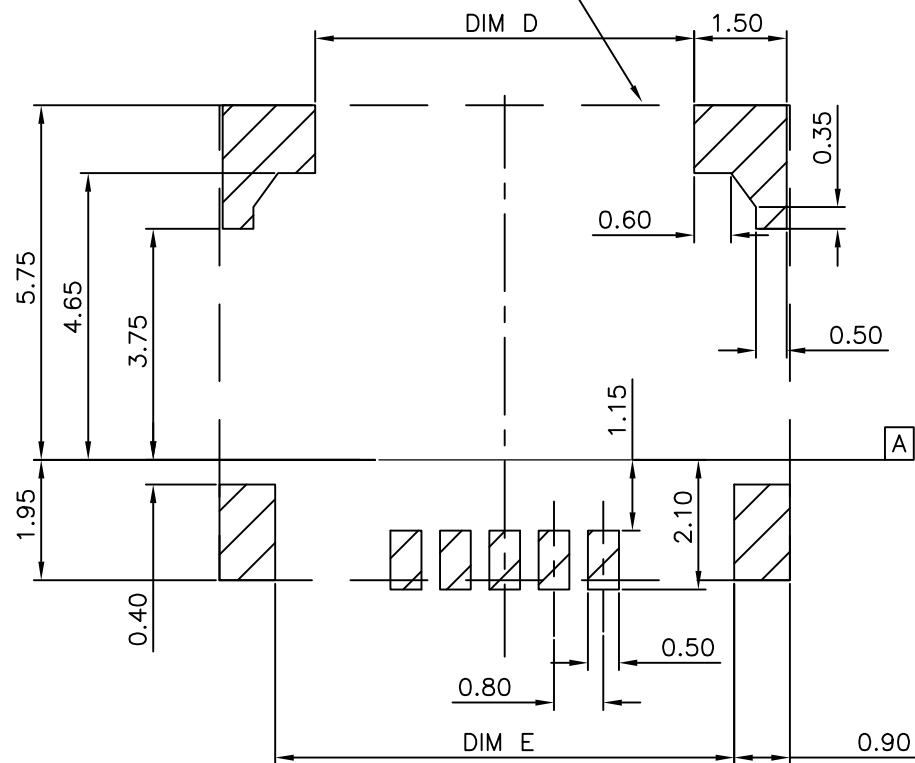
  - 1: GOLD FLASH ON CONTACT AND GOLD FLASH ON SOLDER



QUALITY SYMBOLS	DRAWN BY	DATE				
MAJOR	Tsai, Wang Kun	21/01/18				
CRITICAL	CHECKED BY	DATE	<b>0.80mm Pitch WTB Wafer Conn.</b> <b>SMT S/R S/T Type</b>			
GENERAL TOLERANCES (UNLESS SPECIFIED)	K. HISATOMI	21/01/18				
X. ±0.50	APPROVED BY	DATE	UNITS	SIZE	RFO NO.	
.X ±0.25	Wang,Chun Sheng	21/01/18	mm	A4		
.XX ±0.15			SCALE	SHEET NO.	REV	DWG NO.
.XXX ±0.10			1:1	1 OF 2	B	52200-XXXXX-XXX
ANGLES ±2°						



When drawing wiring inside this, please make the thickness of Pad + 0.03 mm or less



RECOMMENDED P.C.B. LAYOUT  
GENERAL TOLERANCE: ±0.05mm

<b>QUALITY SYMBOLS</b> MAJOR CRITICAL <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X. ±0.15 .X ±0.10 .XX ±0.05 .XXX ±0.02 ANGLES ±1°	DRAWN BY Tsai, Wang Kun 21/01/18	DATE 21/01/18	
	CHECKED BY K, HISATOMI 21/01/18	DATE 21/01/18	
APPROVED BY Wang, Chun Sheng 21/01/18	UNITS mm		SIZE A4
SCALE 1:1	SHEET NO. 2 OF 2	REV B	RFO NO. DWG NO. 52200-XXXXX-XXX